

1.6X0.8mm SMD CHIP LED LAMP

Part Number: APTD1608ZGCK Green



ATTENTION OBSERVE PRECAUTIONS FOR HANDLING **ELECTROSTATIC** DISCHARGE SENSITIVE **DEVICES**

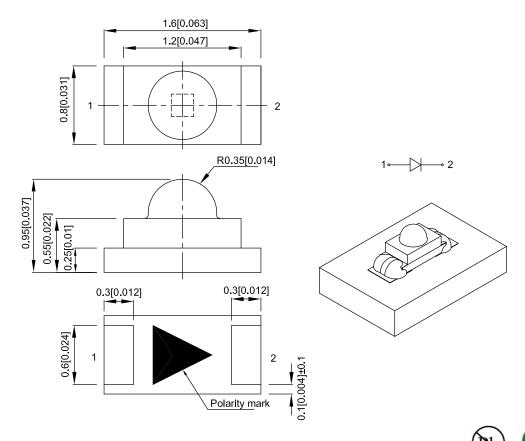
Features

- 1.6mmX0.8mm SMD LED, 0.95mm thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Package: 2000pcs / reel .
- Moisture sensitivity level : level 3.
- RoHS compliant.

Descriptions

- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode.
- Electrostatic discharge and power surge could damage the LEDs.
- It is recommended to use a wrist band or antielectrostatic glove when handling the LEDs.
- All devices, equipments and machineries must be electrically grounded.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.15(0.006") unless otherwise noted.
- The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
 The device has a single mounting surface. The device must be mounted according to the specifications.

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Selection Guide

| Part No. | Emitting Color (Material) | Lens Type | lv (mcd) [2] @ 20mA | | Viewing Angle [1] |
|--------------|---------------------------|-------------|------------------------|------|----------------------|
| | | 2. | Min. | Тур. | 201/2 |
| APTD1608ZGCK | Green (InGaN) | Water Clear | 700 | 1200 | 60° |

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 2. Luminous intensity / luminous Flux: +/-15%.
 3. Luminous intensity value is traceable to CIE127-2007 standards.

Electrical / Optical Characteristics at TA=25°C

| Symbol | Parameter | Emitting Color | Тур. | Max. | Units | Test Conditions |
|--------|--------------------------|----------------|------|------|-------|--------------------|
| λpeak | Peak Wavelength | Green | 515 | | nm | IF=20mA |
| λD [1] | Dominant Wavelength | Green | 525 | | nm | IF=20mA |
| Δλ1/2 | Spectral Line Half-width | Green | 35 | | nm | IF=20mA |
| С | Capacitance | Green | 45 | | pF | VF=0V;f=1MHz |
| VF [2] | Forward Voltage | Green | 3.3 | 4.1 | V | IF=20mA |
| lr | Reverse Current | Green | | 50 | uA | V _R =5V |

- Notes:
 1. Wavelength: +/-1nm.
 2. Forward Voltage: +/-0.1V.
 3. Wavelength value is traceable to CIE127-2007 standards.
- Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

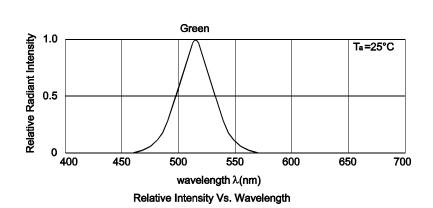
Absolute Maximum Ratings at TA=25°C

| Parameter | Values | Units |
|---|----------------|-------|
| Power dissipation | 102.5 | mW |
| DC Forward Current | 25 | mA |
| Peak Forward Current [1] | 150 | mA |
| Reverse Voltage | 5 | V |
| Electrostatic Discharge Threshold (HBM) | 450 | V |
| Operating Temperature | -40°C To +85°C | |
| Storage Temperature | -40°C To +85°C | |

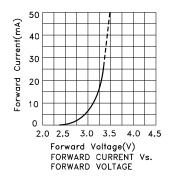
- 1.1/10 Duty Cycle, 0.1ms Pulse Width.
 Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

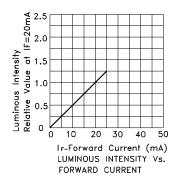
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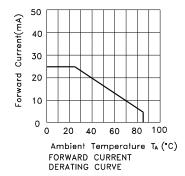
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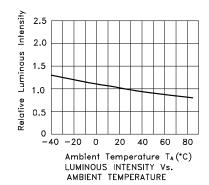


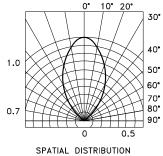
Green APTD1608ZGCK











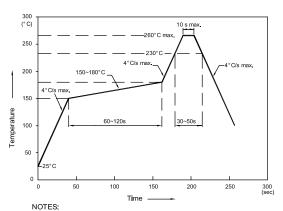
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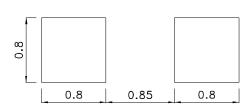
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

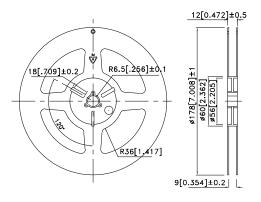


- 1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
- 2.Don't cause stress to the epoxy resin while it is exposed
- to high temperature.
 3.Number of reflow process shall be 2 times or less.

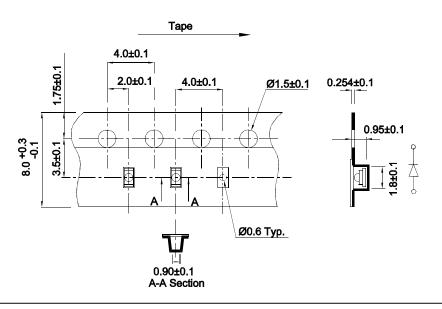
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Reel Dimension



Tape Dimensions (Units : mm)

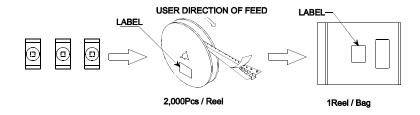


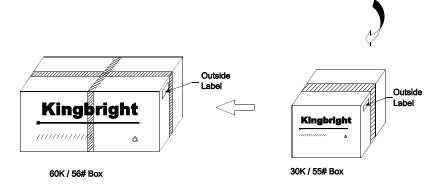
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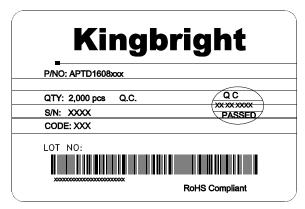


PACKING & LABEL SPECIFICATIONS

APTD1608ZGCK







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